

REMARKS

Claims 1-2, 4-5 and 10-20 are pending in this application. By this Amendment, claims 1, 4 and 13 are amended, and claims 3 and 6-9 are canceled without prejudice to or disclaimer of the material found therein. Reconsideration based on the above amendments and the following Remarks is respectfully requested.

Entry of the amendments is proper under 37 CFR §1.116 since the amendments: (a) place the application in condition for allowance for the reasons discussed herein; (b) do not raise any new issues requiring further search and/or consideration since the amendments amplify issues previously discussed throughout prosecution; and (c) place the application in better form for appeal, should an appeal be necessary. The amendments are necessary and were not earlier presented because they are made in response to arguments raised in the final rejection. Entry of the amendments is thus respectfully requested.

The Office Action rejects claims 1-20 under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 5,117,282 to Salatino. This rejection is respectfully traversed.

Claim 1 recites, among other features, an interconnect substrate over which an interconnect pattern is formed, comprising: a first portion having a rectangular body section; and a second portion, wherein the first portion has end parts as positioning references, the end parts formed by a plurality of projected sections that project from the rectangular body section and that lie in the same plane as the rectangular body section. Claim 13 recites, among other features, a substrate on which the semiconductor chip is mounted, the substrate having a first portion having a rectangular body section and end parts as position references, the end parts formed by a plurality of projected sections that project from the rectangular body section and that lie in the same plane as the rectangular body section.

Salatino discloses only a single portion that projects from the web fingers 21 and 22 in a single direction. Rather than a plurality of projected sections that project from the rectangular

body section and that lie in the same plane as the rectangular body section, as is recited, among other features, in claims 1 and 13. Further, Salatino presupposes, or assumes, mutual alignment in a stack, or mutual horizontal alignment, of layers 21 and 22 (col. 2, lines 58-59 and 67-68) based on the flexibility inherent in the disclosed flexible interconnect circuit web. Salatino neither discloses nor provides motivation for a plurality of end parts as positioning references among adjacent layers in the embodiments shown (emphasis added).

Applicant respectfully submits that Salatino neither discloses nor suggests the plurality of end parts, as recited in claims 1 and 13, as positioning references of a second portion when the interconnect substrate is folded only at one boundary of the first and second portions, the second portion superposed on and inside the first portion.

Applicant further respectfully submits that each of the dependent claims 2, 4-5 and 10-12 includes all of the features recited in claim 1. Further, it is respectfully submitted that each of the dependent claims 14-17 includes all the features recited in claim 13. Finally, Applicant respectfully submits that the method claims 18-20 call for fabricating, inspecting and mounting a semiconductor device using the plurality of end parts described in claims 1 and 13 as positioning references.

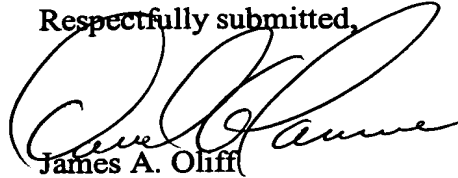
Applicant therefore, respectfully submits that claims 1-2, 4-5 and 10-20 are neither suggested nor motivated by Salatino. Reconsideration and withdrawal of the rejection to claims 1-2, 4-5 and 10-20 under 35 U.S.C. §103(a) are respectfully requested.

In view of the foregoing, it is respectfully submitted that this Application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1-2, 4-5 and 10-20 are earnestly solicited.

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Should the Examiner believe that anything further would be desirable in order to place this Application in even better condition for allowance, the Examiner is invited to contact the Applicant's undersigned representative at the telephone number set forth below.

Respectfully submitted,



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